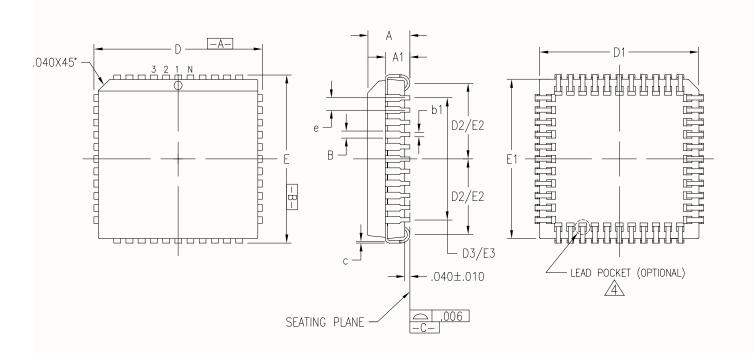
CC44: Ceramic Chip Carrier Package





S Y M B O L	INCHES		
0 L	MIN	NOM	MAX
А	.155	.172	.190
A1	.090		.120
В	.026	.028	.032
b1	.017	.019	.022
С	.006	.007	.012
D/E	.685	.690	.695
D1/E1	.630	.650	.665
D2/E2	.290	.305	.320
D3/E3	.500 REF.		
е	.050 BSC		
N	44		

NOTES:

- 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982.
- 2. LEAD WIDTH DIMENSION INCLUDE LEAD TRIM OFFSET and LEAD FINISH, LEAD FINISH: (HOT SOLDER DIP)
- 3. SYMBOL 'N' IS THE NUMBER OF TERMINALS.
- LEAD POCKET MAY OR MAY NOT EXIST ON THE PACKAGE.
 - 5. THIS PACKAGE MEET DIMENSIONAL REQUIREMENTS OF JEDEC MO-087-AB